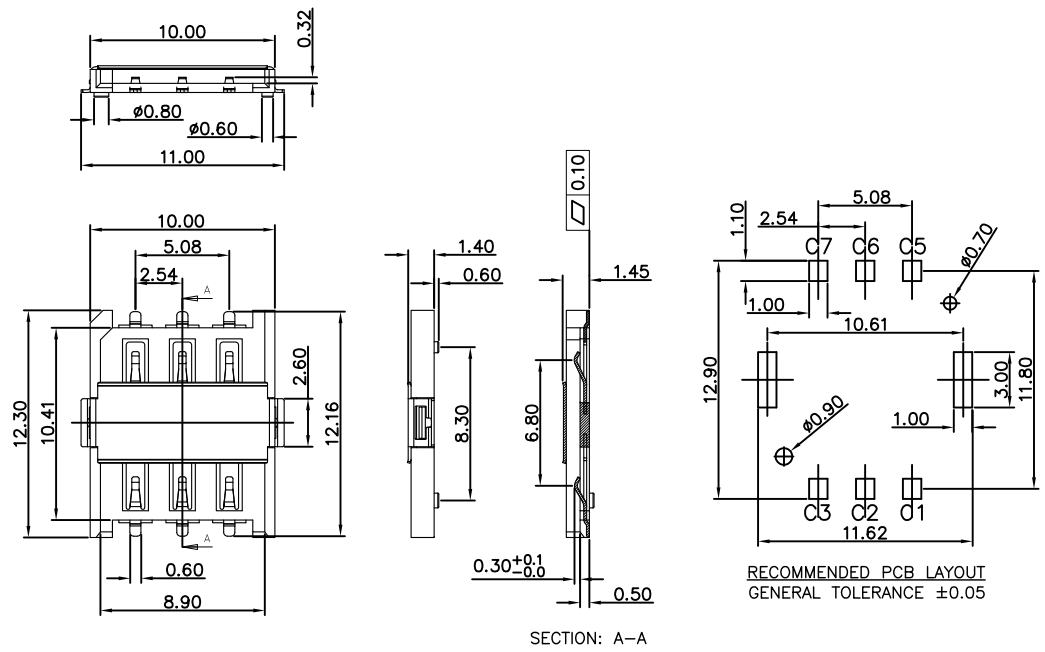
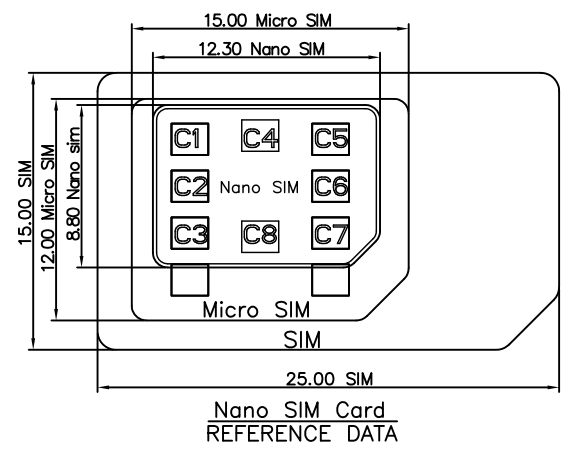


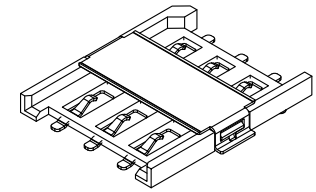
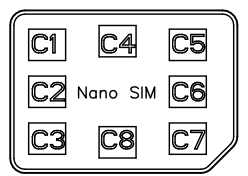
更改 REV	变更内容 MODIFICATION
A	ECXXXXX



- Notes:
- Material:
 - Housing: LCP 30%GF, UL94V-0, Black
 - Contact : Phosphor Bronze, T=0.15mm
 - Shell: SUS304-H, T=0.15mm
 - Plating:
 - Contact:
 - Contact Area: 3U" GOLD PLATED
 - Solder Area: G/F Gold
 - Underplating: Ni overall 50u" Min.
 - Shell:
 - Solder Area: G/F Gold
 - Underplating: Ni overall 50u"
 - Mechanical:
 - Life cycles: 5000.
 - Electrical:
 - Voltage Rating: 30V AC RMS
 - Current Rating: 0.5A AC RMS Max
 - Operating Temperature: -20°C to +80°C
 - Dielectric Withstanding Voltage: 100V AC (60Sec Min)
 - Insulation Resistance: 100MΩ Min
 - Contact Resistance: 30mΩ Max



- C1 --> VCC
- C2 --> RST
- C3 --> CLK
- C5 --> GND
- C6 --> VPP
- C7 --> I/O



GENERAL TOLERANCE		KINGCONN 皇海科技股份有限公司
X± 0.50	X*± 5°	
X± 0.30	X*± 2°	
.XX± 0.20	.XX*± 1°	名 稱(TITLE) Nano SIM CARD CONNECTOR 6PIN SMT TYPE (RoHS)
單位(UNIT) mm	料 號(PART NO.) 7SIMC-FA-0012	圖 號(DWG NO.) 7SIMC-FA-0012-A
審 核(APPROVAL)	核 對(CHECKED)	製 圖(DRAWN)
SCALE 1:1		張 數 SHEET 1 / 1
PROJ.		更 改 REV A